Order Number: MC100ES6111/D Rev 1, 05/2002

Low Voltage 2.5/3.3V Differential ECL/PECL/HSTL Fanout Buffer

The Motorola MC100ES6111 is a bipolar monolithic differential clock fanout buffer. Designed for most demanding clock distribution systems, the MC100ES6111 supports various applications that require distribution of precisely aligned differential clock signals. Using SiGe:C technology and a fully differential architecture, the device offers very low skew outputs and superior digital signal characteristics. Target applications for this clock driver is high performance clock distribution in computing, networking and telecommunication systems.

- 1:10 differential clock distribution
- · 35 ps maximum device skew
- Fully differential architecture from input to all outputs
- SiGe:C technology supports near-zero output skew
- Supports DC to 2.7 GHz operation of clock or data signals
- ECL/PECL compatible differential clock outputs
- ECL/PECL/HSTL compatible differential clock inputs
- Single 3.3V, -3.3V, 2.5V or -2.5V supply
- Standard 32 lead LQFP package
- · Industrial temperature range
- Pin and function compatible to the MC100EP111

MC100ES6111

LOW-VOLTAGE
1:10 DIFFERENTIAL
ECL/PECL/HSTL
CLOCK FANOUT DRIVER



FA SUFFIX 32-LEAD LQFP PACKAGE CASE 873A

Functional Description

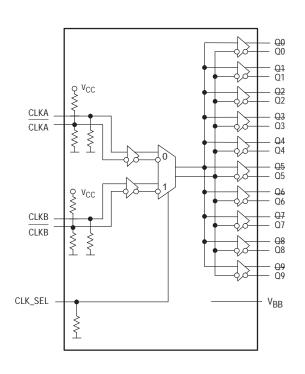
The MC100ES6111 is designed for low skew clock distribution systems and supports clock frequencies up to 2.7 GHz. The device accepts two clock sources. The CLKA input can be driven by ECL or PECL compatible signals, the CLKB input accepts HSTL compatible signals. The selected input signal is distributed to 10 identical, differential ECL/PECL outputs. If VBB is connected to the CLKA input and bypassed to GND by a 10 nF capacitor, the MC100ES6111 can be driven by single-ended ECL/PECL signals utilizing the VBB bias voltage output.

In order to meet the tight skew specification of the device, both outputs of a differential output pair should be terminated, even if only one output is used. In the case where not all ten outputs are used, the output pairs on the same package side as the parts being used on that side should be terminated.

The MC100ES6111 can be operated from a single 3.3V or 2.5V supply. As most other ECL compatible devices, the MC100ES6111 supports positive (PECL) and negative (ECL) supplies. The MC100ES6111 is pin and function compatible to the MC100EP111.







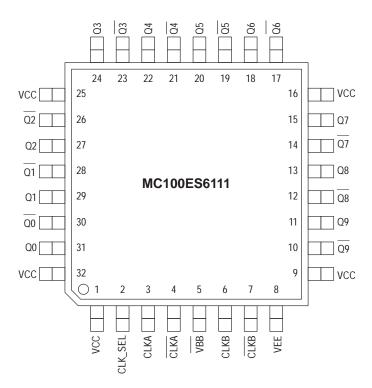


Figure 1. MC100ES6111 Logic Diagram

Figure 2. 32-Lead Package Pinout (Top View)

Table 1. PIN CONFIGURATION

Pin	I/O	Туре	Function	
CLKA, CLKA	Input	ECL/PECL	Differential reference clock signal input	
CLKB, CLKB	Input	HSTL	Alternative differential reference clock signal input	
CLK_SEL	Input	ECL/PECL	Active clock input select	
Q[0-9], Q[0-9]	Output	ECL/PECL	Differential clock outputs	
VEEa	Supply		Negative power supply	
VCC	Supply		Positive power supply. All V _{CC} pins must be connected to the positive power supply for correct DC and AC operation.	
V _{BB}	Output	DC	Reference voltage output for single ended ECL or PECL operation	

a. In ECL mode (negative power supply mode), V_{EE} is either -3.3V or -2.5V and V_{CC} is connected to GND (0V). In PECL mode (positive power supply mode), V_{EE} is connected to GND (0V) and VCC is either +3.3V or +2.5V. In both modes, the input and output levels are referenced to the most positive supply (V_{CC}).

Table 2. FUNCTION TABLE

Control	Default	0	1
CLK_SEL	0	CLKA, CLKA input pair is active. CLKA can be driven by ECL or PECL compatible signals.	CLKB, CLKB input pair is active. CLKB can be driven by HSTL compatible signals.

Table 3. Absolute Maximum Ratingsa

Symbol	Characteristics	Min	Max	Unit	Condition
VCC	Supply Voltage	-0.3	3.6	V	
VIN	DC Input Voltage	-0.3	V _{CC} + 0.3	V	
VOUT	DC Output Voltage	-0.3	V _{CC} + 0.3	V	
I _{IN}	DC Input Current		±20	mA	
lout	DC Output Current		±50	mA	
TS	Storage temperature	-65	125	°C	
T _{Func}	Functional temperature range	T _A = -40	T _J = +110	°C	

a. Absolute maximum continuous ratings are those maximum values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation at absolute-maximum-rated conditions is not implied.

Table 4. General Specifications

Symbol	Characteristics	Min	Тур	Max	Unit	Condition
VTT	Output termination voltage		V _{CC} – 2 ^a		V	
MM	ESD Protection (Machine model)	200			V	
HBM	ESD Protection (Human body model)	4000			V	
CDM	ESD Protection (Charged device model	2000			V	
LU	Latch-up immunity	200			mA	
CIN			4.0		pF	Inputs
θЈΑ	Thermal resistance junction to ambient JESD 51-3, single layer test board JESD 51-6, 2S2P multilayer test board		83.1 73.3 68.9 63.8 57.4 59.0 54.4 52.5 50.4 47.8	86.0 75.4 70.9 65.3 59.6 60.6 55.7 53.8 51.5 48.8	°C/W °C/W °C/W °C/W °C/W °C/W °C/W °C/W	Natural convection 100 ft/min 200 ft/min 400 ft/min 800 ft/min Natural convection 100 ft/min 200 ft/min 400 ft/min 800 ft/min
θЈС	Thermal resistance junction to case		23.0	26.3	°C/W	MIL-SPEC 883E Method 1012.1
TJ	Operating junction temperature ^b (continuous operation) MTBF = 9.1 years			110	°C	

a. Output termination voltage $V_{TT} = 0V$ for $V_{CC} = 2.5V$ operation is supported but the power consumption of the device will increase

b. Operating junction temperature impacts device life time. Maximum continues operating junction temperature should be selected according to the application life time requirements (See application note AN1545 and the application section in this datasheet for more information). The device AC and DC parameters are specified up to 110°C junction temperature allowing the MC100ES6111 to be used in applications requiring industrial temperature range. It is recommended that users of the MC100ES6111 employ thermal modeling analysis to assist in applying the junction temperature specifications to their particular application.

Table 5. PECL/HSTL DC Characteristics ($V_{CC} = 2.5V \pm 5\%$ or $V_{CC} = 3.3V \pm 5\%$, $V_{EE} = GND$, $T_J = 0^{\circ}C$ to + 110°C)

Symbol	Characteristics	Min	Тур	Max	Unit	Condition		
Control inp	Control input CLK_SEL							
V _{IL}	Input voltage low	V _{CC} - 1.810		V _{CC} - 1.475	V			
VIH	Input voltage high	V _{CC} - 1.165		V _{CC} - 0.880	V			
I _{IN}	Input Current ^a			100	μΑ	$V_{IN} = V_{IL}$ or $V_{IN} = V_{IH}$		
Clock inpu	t pair CLKA, CLKA (PECL differential signals)							
VPP	Differential input voltage ^b	0.1		1.3	V	Differential operation		
VCMR	Differential cross point voltage ^C	1.0		V _{CC} - 0.3	V	Differential operation		
IIN	Input Current ^a			100	μΑ	VIN = VIL or VIN = VIH		
Clock inpu	t pair CLKB, CLKB (HSTL differential signals)							
VDIF	Differential input voltaged							
	$V_{CC} = 3.3V$ $V_{CC} = 2.5V$	0.4 0.4			V			
VX	Differential cross point voltage ^e	0.68		0.9	V			
IIN	Input Current			200	μΑ	$V_{IN} = V_X \pm 0.2V$		
PECL cloc	k outputs (Q0-9, Q0-9)							
Vон	Output High Voltage	V _{CC} -1.2	V _{CC} -1.005	V _{CC} -0.7	V	I _{OH} = -30 mA ^f		
VOL	Output Low Voltage $V_{CC} = 3.3V\pm5\%$ $V_{CC} = 2.5V\pm5\%$	V _{CC} -1.9 V _{CC} -1.9	V _{CC} -1.705 V _{CC} -1.705	V _{CC} -1.5 V _{CC} -1.3	V	I _{OL} = -5 mA ^f		
Supply cur	rent and V _{BB}				•			
IEE	Maximum Quiescent Supply Current without output termination current9			100	mA	VEE pin		
V _{BB}	Output reference voltage	V _{CC} - 1.4		V _{CC} - 1.2	V	I _{BB} = 200 μA		

a. Input have internal pullup/pulldown resistors which affect the input current

b. VPP (DC) is the minimum differential input voltage swing required to maintain device functionality

c. V_{CMR} (DC) is the crosspoint of the differential input signal. Functional operation is obtained when the crosspoint is within the V_{CMR} (DC) range and the input swing lies within the V_{PP} (DC) specification.

d. V_{DIF} (DC) is the minimum differential HSTL input voltage swing required for device functionality.

e. V_X (DC) is the crosspoint of the differential HSTL input signal. Functional operation is obtained when the crosspoint is within the V_X (DC) range and the input swing lies within the V_{PP} (DC) specification.

f. Equivalent to a termination of 50Ω to V_{TT}.

g. I_{CC} calculation: I_{CC} = (number of differential output pairs used) x (I_{OH} + I_{OL}) + I_{EE} I_{CC} = (number of differential output pairs used) x (I_{OH} - I_{VT})/ I_{Oad} + (I_{OL} - I_{VT})/ I_{Oad} + I_{EE} .

Table 6. ECL DC Characteristics (VEE = -2.5V \pm 5% or VEE = -3.3V \pm 5%, VCC = GND, TJ = 0°C to + 110°C)

Symbol	Characteristics	Min	Тур	Max	Unit	Condition		
Control inp	Control input CLK_SEL							
V _{IL}	Input voltage low	-1.810		-1.475	V			
VIH	Input voltage high	-1.165		-0.880	V			
I _{IN}	Input Current ^a			100	μА	$V_{IN} = V_{IL}$ or $V_{IN} = V_{IH}$		
Clock inpu	t pair CLKA, CLKB, CLKB (ECL differ	ential signals)						
VPP	Differential input voltageb	0.1		1.3	V	Differential operation		
VCMR	Differential cross point voltage ^C	V _{EE} + 1.0		-0.3	V	Differential operation		
IIN	Input Current ^a			100	μА	$V_{IN} = V_{IL} \text{ or } V_{IN} = V_{IH}$		
ECL clock	outputs (Q0-9, Q0-9)							
Vон	Output High Voltage	-1.2	-1.005	-0.7	V	I _{OH} = -30 mA ^d		
VOL	Output Low Voltage $V_{EE} = -3.3V\pm5\%$ $V_{EE} = -2.5V\pm5\%$	-1.9 -1.9	-1.705 -1.705	-1.5 -1.3	V	IOL = -5 mAd		
Supply cur	Supply current and V _{BB}							
IEE	Maximum Quiescent Supply Current without output termination current ^e			100	mA	V _{EE} pin		
V _{BB}	Output reference voltage	V _{CC} -1.4		V _{CC} -1.2	V	I _{BB} = 200 μA		

a. Input have internal pullup/pulldown resistors which affect the input current

b. VPP (DC) is the minimum differential input voltage swing required to maintain device functionality

c. V_{CMR} (DC) is the crosspoint of the differential input signal. Functional operation is obtained when the crosspoint is within the V_{CMR} (DC) range and the input swing lies within the Vpp (DC) specification. d. Equivalent to a termination of 50Ω to VTT.

e. I_{CC} calculation: I_{CC} = (number of differential output pairs used) x (I_{OH} + I_{OL}) + I_{EE}

I_{CC} = (number of differential output pairs used) x (V_{OH} - V_{TT})/R_{load} + (V_{OL} - V_{TT})/R_{load} + I_{EE}.

Table 7. AC Characteristics (ECL: V_{EE} = -3.3V \pm 5% or V_{EE} = -2.5V \pm 5%, V_{CC} = GND) or (HSTL/PECL: V_{CC} = 3.3V \pm 5% or V_{CC} = 2.5V \pm 5%, V_{FF} = GND, T,J = 0°C to + 110°C) a

Symbol	Characteristics	Min	Тур	Max	Unit	Condition			
Clock input	Clock input pair CLKA, CLKA (PECL or ECL differential signals)								
VPP	Differential input voltageb (peak-to-peak)	0.15		1.3	V				
VCMR	Differential input crosspoint voltage ^C PECL	V _{EE} + 1.0		V _{CC} - 0.3	V				
fCLK	Input Frequency ^d			2.7	GHz	Differential			
tPD	Propagation Delay CLKA or CLKB to Q0-9	280	400	530	ps	Differential			
Clock input	pair CLKB, CLKB (HSTL differential signals)								
VDIF	Differential input voltagee (peak-to-peak)e	0.4		1.0	V				
VX	Differential input crosspoint voltage ^f	VEE + 0.68		VEE + 0.9	V				
fCLK	Input Frequency			2.7	GHz	Differential			
tPD	Propagation Delay CLKB to Q0-9	280	400	530	ps	Differential			
ECL clock	outputs (Q0-9, Q0-9)								
VO(P-P)	Differential output voltage (peak-to-peak) $f_O < 300 \text{ MHz}$ $f_O < 1.5 \text{ GHz}$ $f_O < 2.7 \text{ GHz}$	0.45 0.3 TBD	0.72 0.55 0.37	0.95 0.95 0.95	V V				
tsk(O)	Output-to-output skew			35	ps	Differential			
t _{sk(PP)}	Output-to-output skew (part-to-part)			250	ps	Differential			
tJIT(CC)	Output cycle-to-cycle jitter		TBD						
tsk(P)	Output Pulse skew9			75	ps				
t _r , t _f	Output Rise/Fall Time	0.05		0.3	ns	20% to 80%			

- a. AC characteristics apply for parallel output termination of 50 Ω to $\mbox{V}_{\mbox{TT}}$
- b. Vpp (AC) is the minimum differential ECL/PECL input voltage swing required to maintain AC characteristics including tpd and device-to-device skew
- c. V_{CMR} (AC) is the crosspoint of the differential ECL/PECL input signal. Normal AC operation is obtained when the crosspoint is within the V_{CMR} (AC) range and the input swing lies within the V_{PP} (AC) specification. Violation of V_{CMR} (AC) or V_{PP} (AC) impacts the device propagation delay, device and part-to-part skew
- d. The MC100ES6111 is fully operational up to 3.0 GHz and is characterized up to 2.7 GHz.
- e. V_{DIF} (AC) is the minimum differential HSTL input voltage swing required to maintain AC characteristics including tpd and device-to-device skew.
- f. V_X (AC) is the crosspoint of the differential HSTL input signal. Normal AC operation is obtained when the crosspoint is within the V_X (AC) range and the input swing lies within the V_{DIF} (AC) specification. Violation of V_X (AC) or V_{DIF} (AC) impacts the device propagation delay, device and part-to-part skew
- g. Output pulse skew is the absolute difference of the propagation delay times: $|t_{PLH} t_{PHL}|$.

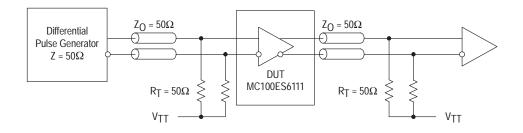


Figure 1. MC100ES6111 AC test reference

APPLICATIONS INFORMATION

Understanding the junction temperature range of the MC100ES6111

To make the optimum use of high clock frequency and low skew capabilities of the MC100ES6111, the MC100ES6111 is specified, characterized and tested for the junction temperature range of T_J=0°C to +110°C. Because the exact thermal performance depends on the PCB type, design, thermal management and natural or forced air convection, the junction temperature provides an exact way to correlate the application specific conditions to the published performance data of this datasheet. The correlation of the junction temperature range to the application ambient temperature range and vice versa can be done by calculation:

$$T_J = T_A + R_{thja} \cdot P_{tot}$$

Assuming a thermal resistance (junction to ambient) of 54.4 °C/W (2s2p board, 200 ft/min airflow, see table 4) and a typical power consumption of 610 mW (all outputs terminated 50 ohms to VTT, VCC=3.3V, frequency independent), the junction temperature of the MC100ES6111 is approximately TA + 33 °C, and the minimum ambient temperature in this example case calculates to -33 °C (the maximum ambient temperature is 77 °C. See Table 8). Exceeding the minimum junction temperature specification of the MC100ES6111 does not have a significant impact on the device functionality. However, the continuous use the MC100ES6111 at high ambient temperatures requires thermal management to not exceed the specified maximum junction temperature. Please see the application note AN1545 for a power consumption calculation guideline.

Table 8: Ambient temperature ranges (Ptot = 610 mW)

R _{thja} (2s2p bo	T _{A, mina}	T _{A, max}	
Natural convection	59.0 °C/W	-36 °C	74 °C
100 ft/min	54.4 °C/W	-33 °C	77 °C
200 ft/min	52.5 °C/W	-32 °C	78 °C
400 ft/min	50.4 °C/W	-30 °C	79 °C
800 ft/min	47.8 °C/W	-29 °C	81 °C

a. The MC100ES6111 device function is guaranteed from $T_{\mbox{\scriptsize A}}\text{=-}40~^{\circ}\mbox{C}$ to $T_{\mbox{\scriptsize J}}\text{=}110~^{\circ}\mbox{C}$

Maintaining Lowest Device Skew

The MC100ES6111 guarantees low output-to-output bank skew of 35 ps and a part-to-part skew of max. 250 ps. To ensure low skew clock signals in the application, both outputs of any differential output pair need to be terminated identically, even if only one output is used. When fewer than all nine output pairs are used, identical termination of all output pairs within the output bank is recommended. If an entire output bank is not used, it is recommended to leave all of these outputs open and unterminated. This will reduce the device power consumption while maintaining minimum output skew.

Power Supply Bypassing

The MC100ES6111 is a mixed analog/digital product. The differential architecture of the MC100ES6111 supports low noise signal operation at high frequencies. In order to maintain its superior signal quality, all V_{CC} pins should be bypassed by high-frequency ceramic capacitors connected to GND. If the spectral frequencies of the internally generated switching noise on the supply pins cross the series resonant point of an individual bypass capacitor, its overall impedance begins to look inductive and thus increases with increasing frequency. The parallel capacitor combination shown ensures that a low impedance path to ground exists for frequencies well above the noise bandwidth.

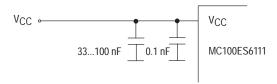
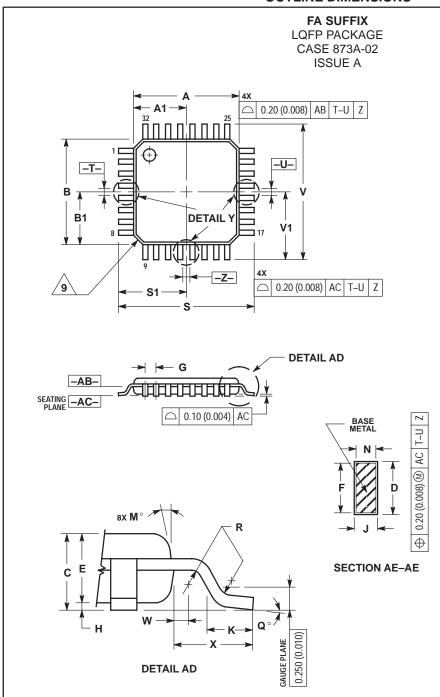
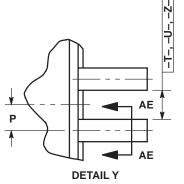


Figure 2. V_{CC} Power Supply Bypass

OUTLINE DIMENSIONS





NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- DATUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD

- 3. DAI IUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.

 4. DATUMS -T-, -U-, AND -Z- TO BE DETERMINED AT DATUM PLANE -AB-.

 5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -AC-.

 6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-.

 7. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.520 (0.020).

 8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076 (0.0003).

 9. EXACT SHAPE OF EACH CORNER MAY VARY FROM DEPICTION.

	MILLIN	METERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	7.000	BSC	0.276	BSC	
A1	3.500	BSC	0.138	BSC	
В	7.000	BSC	0.276	BSC	
B1	3.500	BSC	0.138	BSC	
С	1.400	1.600	0.055	0.063	
D	0.300	0.450	0.012	0.018	
E	1.350	1.450	0.053	0.057	
F	0.300	0.400	0.012	0.016	
G	0.800	BSC	0.031	BSC	
Н	0.050	0.150	0.002	0.006	
J	0.090	0.200	0.004	0.008	
K	0.500	0.700	0.020	0.028	
M	12°	REF	12°	REF	
N	0.090	0.160	0.004	0.006	
P	0.400	BSC	0.016	BSC	
Q	1°	5°	1°	5°	
R	0.150	0.250	0.006	0.010	
S	9.000	BSC	0.354	BSC	
S1	4.500	BSC	0.177 BSC		
V	9.000	9.000 BSC		BSC	
V1	4.500	BSC	0.177 BSC		
W	0.200	REF	0.008	REF	
Х	1.000	REF	0.039	REF	

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